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**(54) SPUTTERING TARGET****(57)Abstract:**

**PURPOSE:** To prevent abnormal electric discharge between target chips at the time of sputtering and to prevent the generation of particles by combining materials of the same kind and/or materials of different kinds with each other and integrating the target chips by diffusion bonding so that a gap is not left.

**CONSTITUTION:** A block is formed by alternately combining materials of the same kind and/or materials of different kinds with each other so that a section is allowed to coincide with that of a desired sputtering target. At this time, the diffusion bonding faces of the materials are cleaned, fixed under pressure and diffusion-bonded by heating. The resulting block is cut to a prescribed thickness to obtain the objective mosaic sputtering target.

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